Dual J-K Flip-Flop

The MC14027B dual J–K flip–flop has independent J, K, Clock (C), Set (S) and Reset (R) inputs for each flip-flop. These devices may be used in control, register, or toggle functions.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Logic Swing Independent of Fanout
- Logic Edge-Clocked Flip-Flop Design Logic state is retained indefinitely with clock level either high or low; information is transferred to the output only on the positive-going edge of the clock pulse
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4027B

$\textbf{MAXIMUM RATINGS} \text{ (Voltages Referenced to V}_{SS}\text{) (Note 2.)}$

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)		
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 3.)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

- 2. Maximum Ratings are those values beyond which damage to the device may occur.
- 3. Temperature Derating: Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, Vin and Vout should be constrained to the range $V_{SS} \le (V_{in} \text{ or } V_{out}) \le V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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P SUFFIX

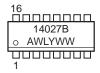
CASE 648



MARKING

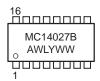


SOIC-16 **D SUFFIX CASE 751B**





SOEIAJ-16 **F SUFFIX CASE 966**



= Assembly Location

WL or L = Wafer Lot YY or Y = Year WW or W = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC14027BCP	PDIP-16	2000/Box
MC14027BD	SOIC-16	2400/Box
MC14027BDR2	SOIC-16	2500/Tape & Reel
MC14027BF	SOEIAJ-16	See Note 1.
MC14027BFEL	SOEIAJ-16	See Note 1.

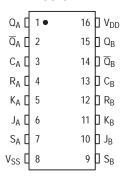
1. For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

TRUTH TABLE

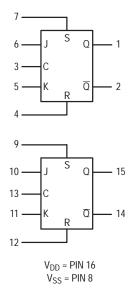
	Inputs						uts*
C†	J	K	S	R	Q _n ‡	Q _{n+1}	Q _{n+1}
	1	Х	0	0	0	1	0
	Х	0	0	0	1	1	0
	0	Х	0	0	0	0	1
	Х	1	0	0	1	0	1
	1	1	0	0	Qo	Qo	Qo
~	Х	Х	0	0	Х	Q _n	$\overline{Q_n}$
Х	Х	Х	1	0	Х	1	0
Х	Х	Х	0	1	Х	0	1
Х	Х	Х	1	1	Х	1	1

No Change

PIN ASSIGNMENT



BLOCK DIAGRAM



X = Don't Care
† = Level Change

^{‡ =} Present State

^{* =} Next State

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

		V _{DD}	- 5	5°C		25°C		125	5°C	
Characteristic	Symbol	Vdc	Min	Max	Min	Typ ^(4.)	Max	Min	Max	Unit
Output Voltage "0" Lev	el V _{OL}	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD} "1" Lev	el V _{OH}	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage "0" Lev $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	el V _{IL}	5.0 10 15	_	1.5 3.0 4.0	_	2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ "1" Lev $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	el V _{IH}	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) \qquad \text{Sour} $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	e I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ Si $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	k l _{OL}	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current	I _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)	I _{DD}	5.0 10 15	_ _ _	1.0 2.0 4.0	_ _ _	0.002 0.004 0.006	1.0 2.0 4.0	_ 	30 60 120	μAdc
Total Supply Current ^(5.) ^(6.) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0 10 15			$I_{T} = (1$).8 μΑ/kHz) f l.6 μΑ/kHz) f 2.4 μΑ/kHz) f	+ I _{DD}			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

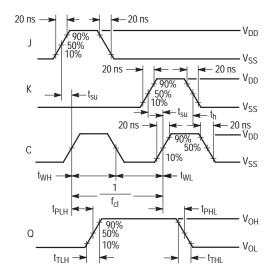
$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.002.

SWITCHING CHARACTERISTICS (7.) $(C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C})$

Characteristic	Symbol	V _{DD}	Min	Тур (8.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_{L} + 25 \text{ ns} $ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} $ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} $	t _{TLH} , t _{THL}	5.0 10 15	_ _ _ _	100 50 40	200 100 80	ns
Propagation Delay Times** Clock to Q, Q t_{PLH} , t_{PHL} = (1.7 ns/pF) C_L + 90 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_L + 42 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_L + 25 ns	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	175 75 50	350 150 100	ns
Set to Q, Q t_{PLH} , t_{PHL} = (1.7 ns/pF) C_L + 90 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_L + 42 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_L + 25 ns		5.0 10 15	_ _ _	175 75 50	350 150 100	
Reset to Q, Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 265 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 67 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 50 \text{ ns}$		5.0 10 15	_ _ _	350 100 75	450 200 150	
Setup Times	t _{su}	5.0 10 15	140 50 35	70 25 17	_ _ _	ns
Hold Times	t _h	5.0 10 15	140 50 35	70 25 17	 _ _	ns
Clock Pulse Width	t _{WH} , t _{WL}	5.0 10 15	330 110 75	165 55 38	_ _ _	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	_ _ _	3.0 9.0 13	1.5 4.5 6.5	MHz
Clock Pulse Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15	_ _ _	_ _ _	15 5.0 4.0	μs
Removal Times Set	t _{rem}	5 10 15	90 45 35	10 5 3	_ _ _ _	ns
Reset		5 10 15	50 25 20	- 30 - 15 - 10	_ _ _	
Set and Reset Pulse Width	t _{WH}	5.0 10 15	250 100 70	125 50 35	_ _ _	ns

The formulas given are for the typical characteristics only at 25°C.
 Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



Inputs R and S low. For the measurement of t_{WH} , l/f_{cl} , and P_D the Inputs J and K are kept high.

Figure 1. Dynamic Signal Waveforms (J, K, Clock, and Output)

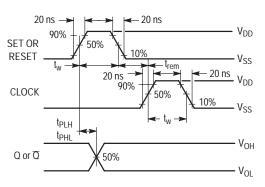
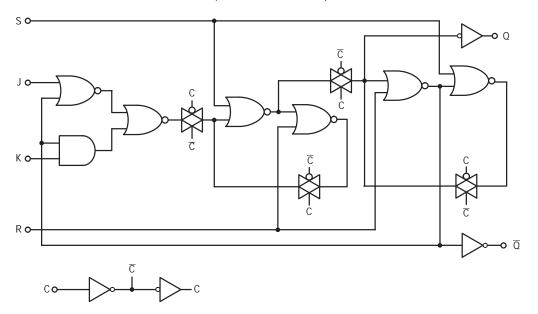


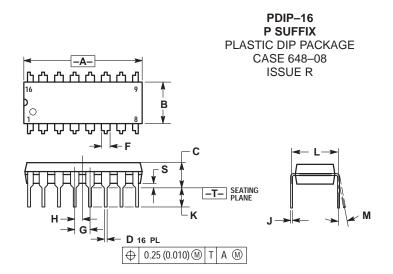
Figure 2. Dynamic Signal Waveforms (Set, Reset, Clock, and Output)

LOGIC DIAGRAM

(1/2 of Device Shown)



PACKAGE DIMENSIONS



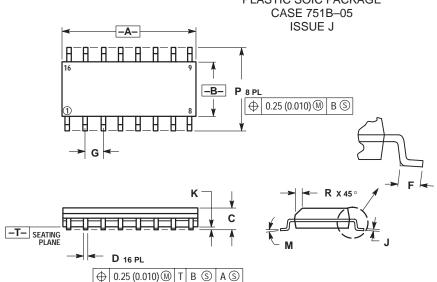
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. DIMENSION LTO CENTER OF LEADS WHEN FORMED PARALLEL. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

5.	ROUNDED	CORNERS	OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01



PLASTIC SOIC PACKAGE CASE 751B-05



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

 5. DIMENSION D POSS NOT INCLUDE DAMAGE.

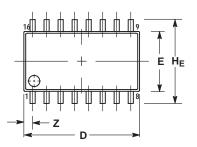
- PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.

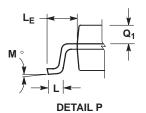
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050) BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

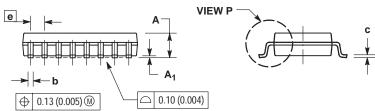
PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX**

PLASTIC EIAJ SOIC PACKAGE CASE 966-01 ISSUE O







- OTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Ε	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050) BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

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